



## Microsemi SoC Corp.

### USE OF PURE TIN COMPONENTS INTENDED FOR SPACE APPLICATIONS

There are several directives and government regulations to reduce the use of hazardous substances such as lead. In reducing the use of lead, many suppliers have substituted pure tin plating in their products. The use of pure tin plating may cause several problems including tin whisker growth which may present a problem when this material is used in space applications. Microsemi SoC Corp., as a policy, does not use or intend to use pure tin plating on any hermetic devices that have been shipped or for any future shipments.

Microsemi SoC has not delivered hermetic packages with pure tin plating or solder and will not ship hermetic devices in the future with pure tin plating. Microsemi SoC's hermetic products containing tin metal shall not exceed 97% purity.

If you have any further questions about the risks of tin whisker growth in space applications, please refer to the web site below, or contact Microsemi SoC [Tech Support](#) for assistance.

<http://nepp.nasa.gov/whisker/reference/reference.html>

Corporate Operations Quality

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